

300mA CMOS LDO

Features

- Extremely Low Supply Current (50 μ A, Typ.)
- Very Low Dropout Voltage
- 300mA Output Current
- High Output Voltage Accuracy
- Standard or Custom Output Voltages
- Over Current and Over Temperature Protection

Applications

- Battery Operated Systems
- Portable Computers
- Medical Instruments
- Instrumentation
- Cellular/GSM/PHS Phones
- Linear Post-Regulators for SMPS
- Pagers

Device Selection Table

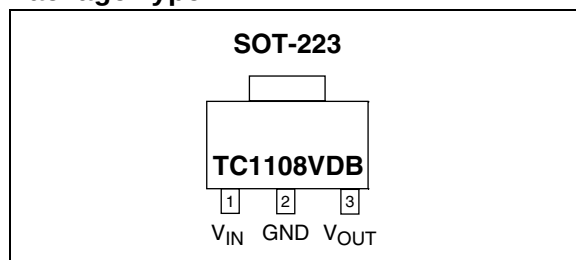
Part Number	Package	Junction Temp. Range
TC1108-xxVDB	3-Pin SOT-223	-40°C to +125°C

NOTE: xx indicates output voltages

Available Output Voltages: 2.5, 2.8, 3.0, 3.3, 5.0.

Other output voltages are available. Please contact Microchip Technology Inc. for details.

Package Type



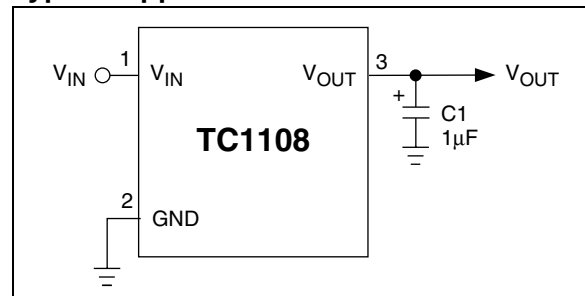
General Description

The TC1108 is a fixed output, high accuracy (typically $\pm 0.5\%$) CMOS low dropout regulator. Total supply current is typically 50 μ A at full load (20 to 60 times lower than in bipolar regulators).

TC1108 key features include ultra low noise operation, very low dropout voltage (typically 240mV at full load), and fast response to step changes in load.

The TC1108 incorporates both over temperature and over current protection. The TC1108 is stable with an output capacitor of only 1 μ F and has a maximum output current of 300mA. It is available in a SOT-223 package.

Typical Application



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings*

Input Voltage6.5V
Output Voltage..... ($V_{SS} - 0.3V$) to ($V_{IN} + 0.3V$)
Power Dissipation.....Internally Limited (**Note 6**)
Maximum Voltage on Any Pin $V_{IN} + 0.3V$ to $-0.3V$
Operating Temperature Range..... $-40^{\circ}C < T_J < 125^{\circ}C$
Storage Temperature..... $-65^{\circ}C$ to $+150^{\circ}C$

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

TC1108 ELECTRICAL SPECIFICATIONS

Electrical Characteristics: $V_{IN} = V_{OUT} + 1V$, $I_L = 100\mu A$, $C_L = 3.3\mu F$, $T_A = 25^{\circ}C$, unless otherwise noted. Boldface type specifications apply for junction temperatures of $-40^{\circ}C$ to $+125^{\circ}C$.						
Symbol	Parameter	Min	Typ	Max	Units	Test Conditions
V_{IN}	Input Operating Voltage	2.7	—	6.0	V	Note 7
I_{OUTMAX}	Maximum Output Current	300	—	—	mA	
V_{OUT}	Output Voltage	— $V_R - 2.5\%$	$V_R \pm 0.5\%$ —	— $V_R + 2.5\%$	V	Note 1
$\Delta V_{OUT}/\Delta T$	V_{OUT} Temperature Coefficient	—	40	—	ppm/ $^{\circ}C$	Note 2
$\Delta V_{OUT}/\Delta V_{IN}$	Line Regulation	—	0.05	0.35	%	$(V_R + 1V) \leq V_{IN} \leq 6V$
$\Delta V_{OUT}/I_{OUT}$	Load Regulation	—	0.5	2.0	%	$I_L = 0.1mA$ to I_{OUTMAX} (Note 3)
$V_{IN}-V_{OUT}$	Dropout Voltage	— — —	20 80 240	30 160 480	mV	$I_L = 0.1mA$ $I_L = 100mA$ $I_L = 300mA$ (Note 4)
I_{DD}	Supply Current	—	50	90	μA	
PSRR	Power Supply Rejection Ratio	—	60	—	dB	$F_{RE} \leq 1kHz$
I_{OUTSC}	Output Short Circuit Current	—	550	650	mA	$V_{OUT} = 0V$
$\Delta V_{OUT}/\Delta P_D$	Thermal Regulation	—	0.04	—	V/W	Note 5
eN	Output Noise	—	260	—	nV/ $\sqrt{Hz}$	$F = 10kHz$, $C_{OUT} = 1\mu F$, $R_{LOAD} = 50\Omega$

Note 1: V_R is the regulator output voltage setting.

Note 2: $TC V_{OUT} = \frac{(V_{OUTMAX} - V_{OUTMIN}) \times 10^6}{V_{OUT} \times \Delta T}$

- Note 3:** Regulation is measured at a constant junction temperature using low duty cycle pulse testing. Load regulation is tested over a load range from 0.1mA to the maximum specified output current. Changes in output voltage due to heating effects are covered by the thermal regulation specification.
- Note 4:** Dropout voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal value measured at a 1V differential.
- Note 5:** Thermal Regulation is defined as the change in output voltage at a time T after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a current pulse equal to I_{LMAX} at $V_{IN} = 6V$ for $T = 10$ msec.
- Note 6:** The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction-to-air (i.e., T_A , T_J , θ_{JA}). Exceeding the maximum allowable power dissipation causes the device to initiate thermal shutdown. Please see Section 4.0 Thermal Considerations for more details.
- Note 7:** The minimum V_{IN} has to justify the conditions: $V_{IN} \geq V_R + V_{DROPOUT}$ and $V_{IN} \geq 2.7V$ for $I_L = 0.1mA$ to I_{OUTMAX} .

2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

TABLE 2-1: PIN FUNCTION TABLE

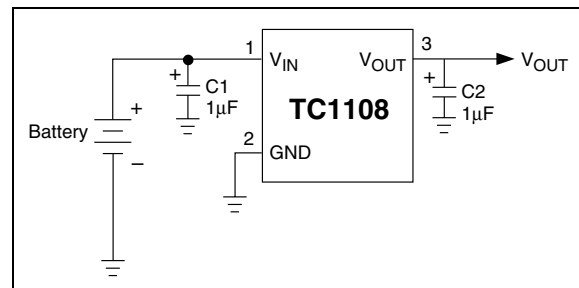
Pin No. (3-Pin SOT-223)	Symbol	Description
1	V_{IN}	Unregulated supply input.
2	GND	Ground terminal.
3	V_{OUT}	Regulated voltage output.

3.0 DETAILED DESCRIPTION

The TC1108 is a precision, fixed output LDO. Unlike bipolar regulators, the TC1108's supply current does not increase with load current. In addition, V_{OUT} remains stable and within regulation over the entire 0mA to I_{OUTMAX} operating load current range, (an important consideration in RTC and CMOS RAM battery back-up applications).

Figure 3-1 shows a typical application circuit.

FIGURE 3-1: TYPICAL APPLICATION CIRCUIT



3.1 Output Capacitor

A 1µF (min) capacitor from V_{OUT} to ground is required. The output capacitor should have an effective series resistance greater than 0.1Ω and less than 5.0Ω. A 1µF capacitor should be connected from V_{IN} to GND if there is more than 10 inches of wire between the regulator and the AC filter capacitor, or if a battery is used as the power source. Aluminum electrolytic or tantalum capacitor types can be used. (Since many aluminum electrolytic capacitors freeze at approximately -30°C, solid tantalums are recommended for applications operating below -25°C.) When operating from sources other than batteries, supply-noise rejection and transient response can be improved by increasing the value of the input and output capacitors and employing passive filtering techniques.

4.0 THERMAL CONSIDERATIONS

4.1 Thermal Shutdown

Integrated thermal protection circuitry shuts the regulator off when die temperature exceeds 150°C. The regulator remains off until the die temperature drops to approximately 140°C.

4.2 Power Dissipation

The amount of power the regulator dissipates is primarily a function of input and output voltage, and output current. The following equation is used to calculate worst case actual power dissipation:

EQUATION 4-1:

$$P_D \approx (V_{INMAX} - V_{OUTMIN})I_{LOADMAX}$$

Where:

P_D = Worst case actual power dissipation
 V_{INMAX} = Maximum voltage on V_{IN}
 V_{OUTMIN} = Minimum regulator output voltage
 $I_{LOADMAX}$ = Maximum output (load) current

The maximum allowable power dissipation (Equation 4-2) is a function of the maximum ambient temperature (T_{AMAX}), the maximum allowable die temperature (T_{JMAX}) and the thermal resistance from junction-to-air (θ_{JA}).

EQUATION 4-2:

$$P_{DMAX} = \frac{(T_{JMAX} - T_{AMAX})}{\theta_{JA}}$$

Where all terms are previously defined.

Table 4-1 shows various values of θ_{JA} for the TC1108 versus board copper area.

TABLE 4-1: THERMAL RESISTANCE GUIDELINES FOR TC1108

Copper Area (Topside)*	Copper Area (Backside)	Board Area	Thermal Resistance (θ_{JA})
2500 sq mm	2500 sq mm	2500 sq mm	45°C/W
1000 sq mm	2500 sq mm	2500 sq mm	45°C/W
225 sq mm	2500 sq mm	2500 sq mm	53°C/W
100 sq mm	2500 sq mm	2500 sq mm	59°C/W
1000 sq mm	1000 sq mm	1000 sq mm	52°C/W
1000 sq mm	0 sq mm	1000 sq mm	55°C/W

NOTE: *Tab of device attached to topside copper

Equation 4-1 can be used in conjunction with Equation 4-2 to ensure regulator thermal operation is within limits. For example:

Given:

$$\begin{aligned} V_{INMAX} &= 3.3V + 10\% \\ V_{OUTMIN} &= 2.7V - 0.5\% \\ I_{LOADMAX} &= 275mA \\ T_{JMAX} &= 125^\circ C \\ T_{AMAX} &= 95^\circ C \\ \theta_{JA} &= 59^\circ C/W \end{aligned}$$

Find: 1. Actual power dissipation
 2. Maximum allowable dissipation

Actual power dissipation:

$$\begin{aligned} P_D &\approx (V_{INMAX} - V_{OUTMIN})I_{LOADMAX} \\ &= [(3.3 \times 1.1) - (2.7 \times .995)]275 \times 10^{-3} \\ &= 260mW \end{aligned}$$

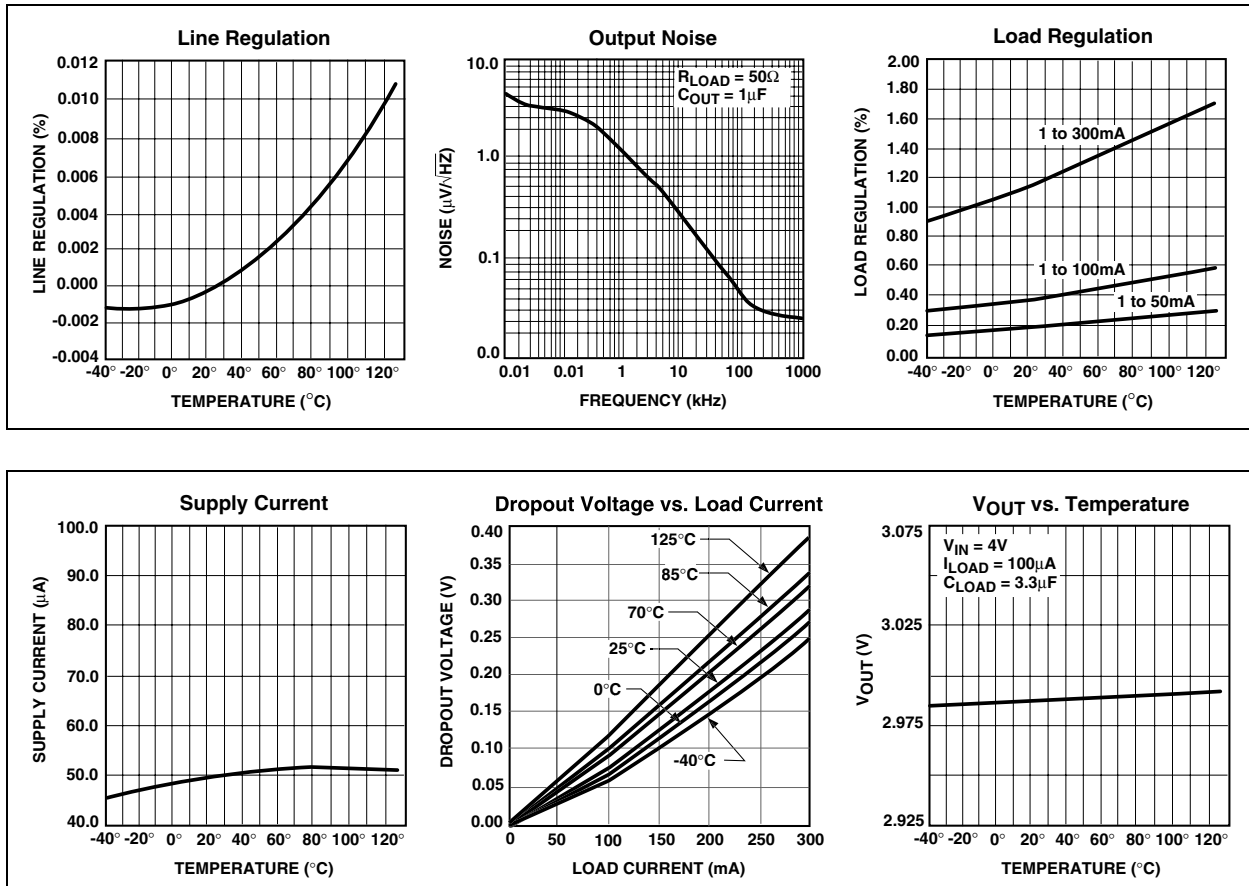
Maximum allowable power dissipation:

$$\begin{aligned} P_{DMAX} &= \frac{(T_{JMAX} - T_{AMAX})}{\theta_{JA}} \\ &= \frac{(125 - 95)}{59} \\ &= 508mW \end{aligned}$$

In this example, the TC1108 dissipates a maximum of 260mW; below the allowable limit of 508mW. In a similar manner, Equation 4-1 and Equation 4-2 can be used to calculate maximum current and/or input voltage limits. For example, the maximum allowable V_{IN} , is found by substituting the maximum allowable power dissipation of 508mW into Equation 4-1, from which $V_{INMAX} = 4.6V$.

5.0 TYPICAL CHARACTERISTICS

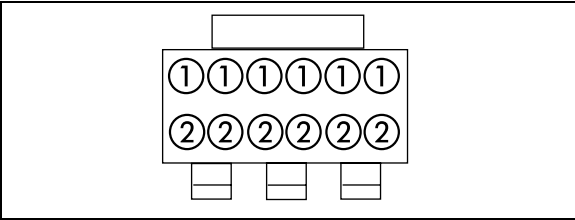
Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.



TC1108

6.0 PACKAGING INFORMATION

6.1 Package Marking Information



“1” = part number code

“2” = represents temperature + date code + lot identity
+ subcontractor identity

TC1108 (V)	Code
TC1108-2.5VDB	110825
TC1108-2.8VDB	110828
TC1108-3.0VDB	110830
TC1108-3.3VDB	110833
TC1108-5.0VDB	110850

6.2 Taping Form

Component Taping Orientation for 3-Pin SOT-223 Devices

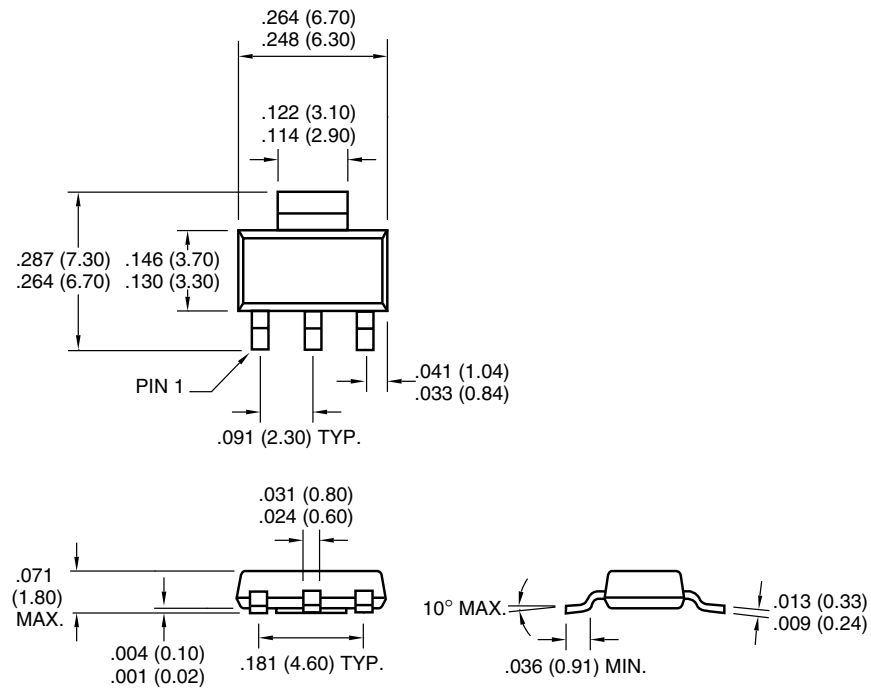
A diagram showing the standard reel component orientation for TR suffix devices. It depicts a carrier tape with five SOT-223 components. An arrow labeled 'User Direction of Feed' points to the right. A label 'Device Marking' points to the first component. A label 'PIN 1' points to the first pin of the first component. A label 'P' indicates the pitch between components. A label 'W' indicates the carrier width. Below the diagram, text reads: 'Standard Reel Component Orientation for TR Suffix Device (Mark Right Side Up)'.

Carrier Tape, Number of Components Per Reel and Reel Size

Package	Carrier Width (W)	Pitch (P)	Part Per Full Reel	Reel Size
3-Pin SOT-223	12 mm	8 mm	4000	13 in

6.3 Package Dimensions

3-Pin SOT-223



Dimensions: inches (mm)

TC1108

NOTES:

SALES AND SUPPORT

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
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Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

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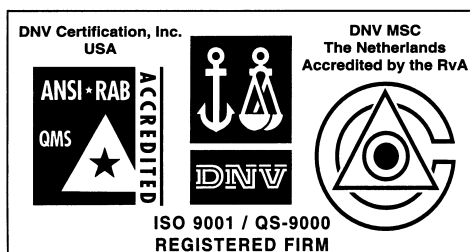
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